

06-29-2004

Substitute Form PTO-1595



Attorney Docket No.: 0055/070001

102779233

IT

PATENTS ONLY

621-04

Commissioner of Patents and Trademarks: Please record the attached copies of an original document.

19587 U.S. PTO  
10/870912  
062104

1. Name of conveying party(ies):  
Shintaro NAKASHIMA

2. Name and address of receiving party(ies):  
Nichia Corporation  
491-100 Oka, Kaminaka-cho  
Anan-shi, Tokushima-ken  
774-8601 JAPAN

Additional name(s) attached? ☐ Yes ☒ No

3. Nature of conveyance:  
☒ Assignment  
☐ Merger  
☐ Security Agreement  
☐ Change of Name  
☐ Other:

Additional names/addresses attached? ☐ Yes ☒ No

Execution Date: June 21, 2004

4. Application number(s) or patent number(s):

10870912

If this document is being filed with a new application, the execution date of the application is: June 21, 2004

A. Patent Application No.(s):

B. Patent No.(s):

Additional numbers attached? ☐ Yes ☒ No

5. Name/address of party to whom correspondence concerning document should be mailed:

Randolph A. Smith  
SMITH PATENT OFFICE  
1901 Pennsylvania Ave., N.W.  
Suite 200  
Washington, D.C. 20006-3433

6. Total number of applications/patents involved: 1

7. Total fee (37 CFR 3.41): \$40

☐ Enclosed

☒ Authorized to charge deposit account

8. Deposit account number: 19-2586

If the fee above is being charged to deposit account, a duplicate copy of this cover sheet is attached. Please apply any additional charges, or any credits, to our Deposit Account No. 19-2586.

DO NOT USE THIS SPACE

9. Statement and signature: *To the best of my knowledge and belief, the foregoing information is true and correct and the attached is a true copy of the original document.*

Randolph A. Smith  
Name of Person Signing

Signature

June 21, 2004  
Date

Total number of pages including cover sheet, attachments, and document: 3

06/28/2004 8TON11 00000063 192586 10870912  
01 FC:8021 40.00 BA

PATENT  
REEL: 015497 FRAME: 0544

## ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the undersigned hereby assign(s), transfer(s) and set(s) over to:

Nichia Corporation

having the address:

491-100 Oka, Kaminaka-cho, Anan-shi  
Tokushima-ken 774-8601 JAPAN

(hereinafter collectively designated as the "ASSIGNEE"), its successors and assigns, the entire right, title, and interest for the United States in the invention, and all applications for patent and any Letters Patent which may be granted therefore, including said application, and all United States Letters Patents which may be granted therefore, and all divisions, reissues, continuations and extensions thereof, the said interest being the entire ownership of said Letters Patent when granted to be held by said ASSIGNEE, its successors, assigns or their legal representatives, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been and enjoyed by Assignor(s) if this assignment had not been made, the application being known by the Title:

MOLDED PACKAGE AND SEMICONDUCTOR DEVICE USING MOLDED PACKAGE

Attorney Docket No. 0055/070001

for which the undersigned has/have executed an application for patent in the United States of America on the same day herewith. Where this instrument is not filed concurrently with the application, the following identifying information may be added after execution:

Serial No.

Filing Date: June 21, 2004

1. The undersigned hereby agree(s) to sign and execute any further documents and instruments which may be necessary, lawful and proper in the prosecution of said above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue application or in any amendments, extension of interference proceedings, or otherwise to secure the title thereto to the ASSIGNEE.

2. The undersigned agree(s) to execute all papers and documents and perform any act that may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

3. The undersigned agree(s) to perform all affirmative acts that may be necessary to obtain a grant of a valid United States patent to the ASSIGNEE.

4. The undersigned hereby authorize(s) and request(s) the Commissioner of Patents and Trademarks in the United States to issue any and all Letters Patents resulting from said application or any division or divisions or continuing applications thereof to the said ASSIGNEE.

5. The undersigned hereby grant(s) to Randolph A. Smith and Smith Patent Office the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

June 21, 2004

Date

Shintaro NAKASHIMA

Typed Name: Shintaro NAKASHIMA